

## STGD7NB60S

# N-CHANNEL 7A - 600V - DPAK Power MESH<sup>TM</sup> IGBT

TYPE	V <sub>CES</sub>	V <sub>CE(sat)</sub>	I <sub>C</sub>
STGD7NB60S	600 V	< 1.6 V	7 A

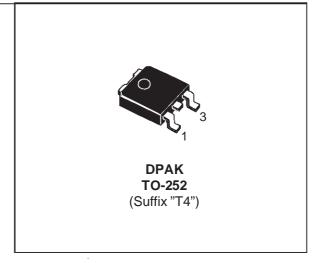
- HIGH INPUT IMPEDANCE (VOLTAGE DRIVEN)
- VERY LOW ON-VOLTAGE DROP (Vcesat)
- HIGH CURRENT CAPABILITY
- OFF LOSSES INCLUDE TAIL CURRENT

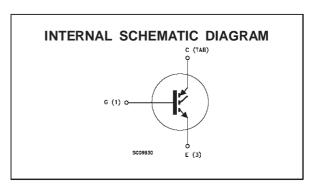
#### **DESCRIPTION**

Using the latest high voltage technology based on a patented strip layout, SGS-Thomson has designed an advanced family of IGBTs, the PowerMESH<sup>TM</sup> IGBTs, with outstanding perfomances. The suffix "S" identifies a family optimized to achieve minimum on-voltage drop for low frequency applications (<1kHz).

#### **APPLICATIONS**

- LIGHT DIMMER
- STATIC RELAYS
- MOTOR CONTROL





#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CES</sub>	Collector-Emitter Voltage (V <sub>GS</sub> = 0)	600	V
V <sub>ECR</sub>	Reverse Battery Protection	20	V
$V_{GE}$	Gate-Emitter Voltage	± 20	V
Ic	Collector Current (continuous) at T <sub>c</sub> = 25 °C	15	А
Ic	Collector Current (continuous) at T <sub>c</sub> = 100 °C	7	А
I <sub>CM</sub> (●)	Collector Current (pulsed)	60	А
P <sub>tot</sub>	Total Dissipation at T <sub>c</sub> = 25 °C	55	W
	Derating Factor	0.4	W/°C
T <sub>stg</sub>	Storage Temperature	-65 to 150	°C
Tj	Max. Operating Junction Temperature	-40 to 150	°C

(•) Pulse width limited by safe operating area

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### THERMAL DATA

R <sub>thj-case</sub>	Thermal	Resistance	Junction-case	Max	2.27	°C/W
R <sub>thj-amb</sub>	Thermal	Resistance	Junction-ambient	Max	100	°C/W
R <sub>thc-sink</sub>	Thermal	Resistance	Case-sink	Тур	1.5	°C/W

# **ELECTRICAL CHARACTERISTICS** ( $T_j = 25$ °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>BR(CES)</sub>	Collector-Emitter Breakdown Voltage	$I_C = 250 \ \mu A$ $V_{GE} = 0$	600			V
V <sub>BR(ECR)</sub>	Emitter-Collector Breakdown Voltage	I <sub>C</sub> = 1 mA V <sub>GE</sub> = 0	20			V
I <sub>CES</sub>	Collector cut-off (V <sub>GE</sub> = 0)	$V_{CE} = Max Rating$ $T_j = 25  ^{\circ}C$ $V_{CE} = Max Rating$ $T_j = 125  ^{\circ}C$			10 100	μA μA
I <sub>GES</sub>	Gate-Emitter Leakage Current (V <sub>CE</sub> = 0)	$V_{GE} = \pm 20 \text{ V}$ $V_{CE} = 0$			± 100	nA

## ON (\*)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>GE(th)</sub>	Gate Threshold Voltage	$V_{CE} = V_{GE}$ $I_C = 250 \mu A$	2.5		5	V
V <sub>CE(SAT)</sub>	Collector-Emitter Saturation Voltage	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$		1 1.2 1.1	1.4 1.6	> >

### **DYNAMIC**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
	Forward Transconductance	V <sub>CE</sub> =25 V I <sub>C</sub> = 7 A	5			S
C <sub>ies</sub> C <sub>oes</sub> C <sub>res</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{CE} = 25 \text{ V}$ f = 1 MHz $V_{GE} = 0$		610 65 12	780 85 15	pF pF pF
Q <sub>G</sub>	Gate Charge	$V_{CE} = 400 \text{ V}  I_{C} = 7 \text{ A}  V_{GE} = 15 \text{ V}$		33		nC
I <sub>CL</sub>	Latching Current	$V_{clamp} = 480 \text{ V}  RG=1k\Omega$ $T_j = 125 \text{ °C}$	15			А

### **SWITCHING ON**

Symbol	Parameter	Test Conditions			Тур.	Max.	Unit
t <sub>d(on)</sub>	Delay Time Rise Time	V <sub>CC</sub> = 480 V V <sub>GE</sub> = 15 V	$I_C = 7 A$ $R_G = 1 K\Omega$		0.7 0.46		μs us
	Turn-on Current Slope	$V_{CC} = 480 \text{ V}$ $R_G = 1 \text{ K}\Omega$	I <sub>C</sub> = 7 A V <sub>GE</sub> = 15 V		8		A/μs
Eon	Turn-on Switching Losses	$T_j = 125$ °C	v GE = 15 V		0.4		mJ

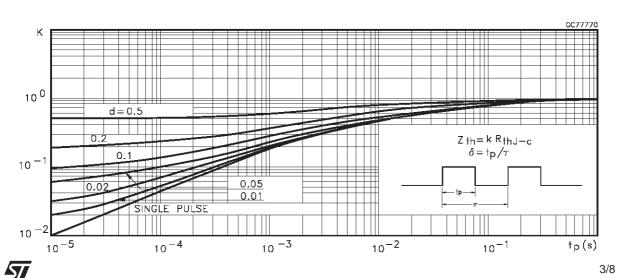
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## **ELECTRICAL CHARACTERISTICS** (continued)

**SWITCHING OFF** 

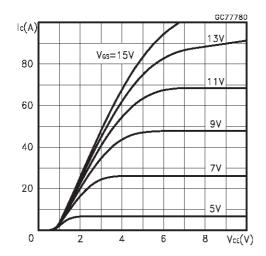
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
$\begin{array}{c} t_c \\ t_r(v_{off}) \\ t_f \\ E_{off}(^{**}) \end{array}$	Cross-Over Time Off Voltage Rise Time Fall Time Turn-off Switching Loss	$V_{CC} = 480 \text{ V}$ $I_{C} = 7 \text{ A}$ $V_{GE} = 100 \Omega$ $V_{GE} = 15 \text{ V}$	,	2.2 1.2 1.2 3.5		μs μs μs mJ
$\begin{array}{c} t_c \\ t_r(v_{off}) \\ t_f \\ E_{off}(^{**}) \end{array}$	Cross-Over Time Off Voltage Rise Time Fall Time Turn-off Switching Loss	$V_{CC} = 480 \text{ V}$ $I_{C} = 7 \text{ A}$ $V_{GE} = 100 \Omega$ $V_{GE} = 15 \text{ N}$ $V_{GE} = 15 \text{ N}$	,	3.8 1.2 1.9 5.3		μs μs μs mJ

## Thermal Impedance

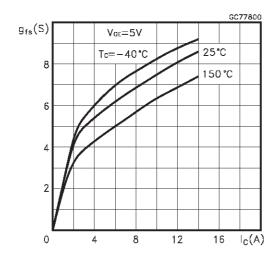


<sup>(•)</sup> Pulse width limited by safe operating area
(\*) Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %
(\*\*)Losses Include Also The Tail (Jedec Standardization)

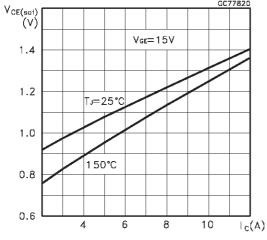
### **Output Characteristics**



#### Transconductance

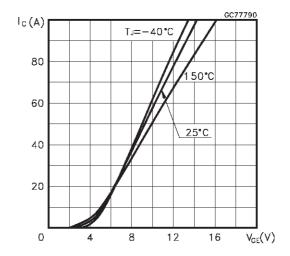


Collector-Emitter On Voltage vs Collector Current

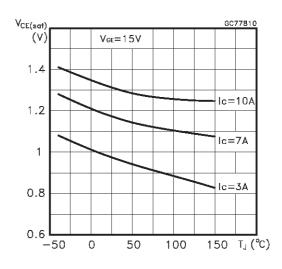


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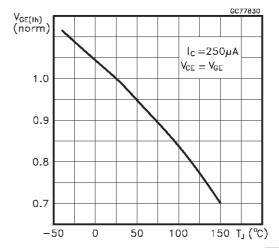
#### **Transfer Characteristics**



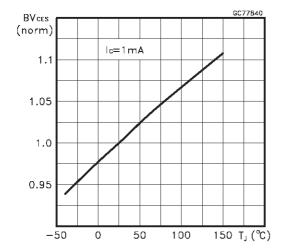
Collector-Emitter On Voltage vs Temperature



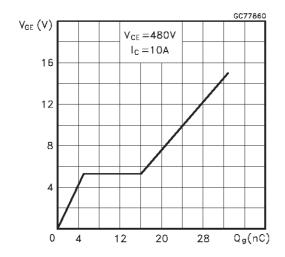
Gate Threshold vs Temperature



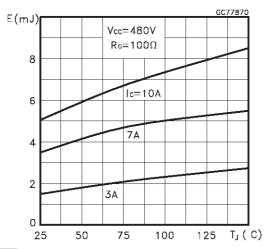
### Normalized Breakdown Voltage vs Temperature



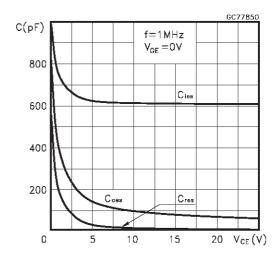
## Gate Charge vs Gate-Emitter Voltage



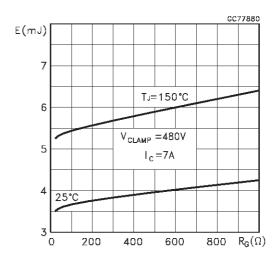
## Off Losses vs Temperature



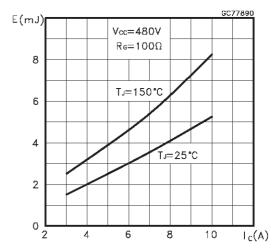
### Capacitance Variations



Off Losses vs Gate Resistance



Off Losses vs Collector Current



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## Switching Off Safe Operatin Area

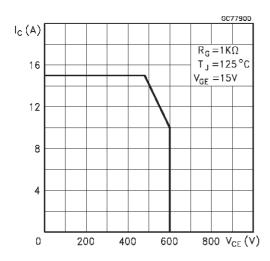
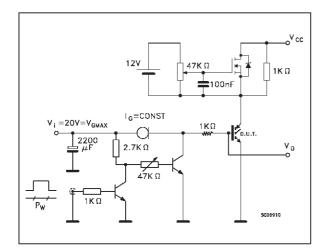


Fig. 1: Gate Charge test Circuit



**Fig. 2:** Switching Times Test Circuit For Resistive Load

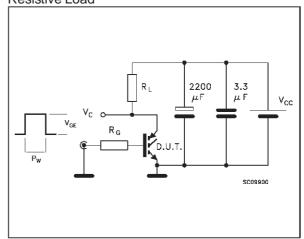
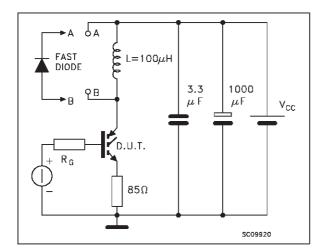


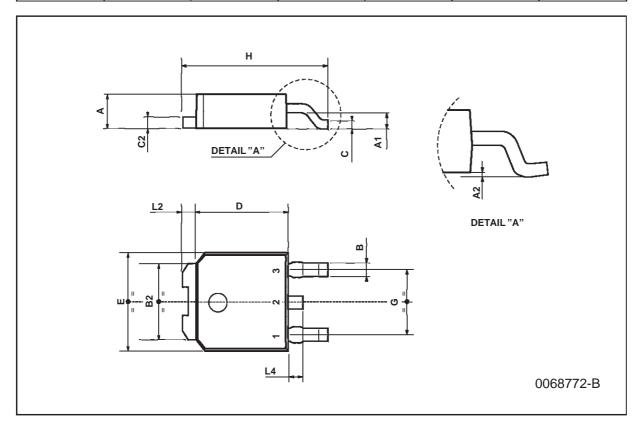
Fig. 3: Test Circuit For Inductive Load Switching



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# TO-252 (DPAK) MECHANICAL DATA

DIM.		mm			inch	
Diwi.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A2	0.03		0.23	0.001		0.009
В	0.64		0.9	0.025		0.035
B2	5.2		5.4	0.204		0.212
С	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
E	6.4		6.6	0.252		0.260
G	4.4		4.6	0.173		0.181
Н	9.35		10.1	0.368		0.397
L2		0.8			0.031	
L4	0.6		1	0.023		0.039



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